IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. Claims 1, 2, 25, 26, 29, 31, and 35 have been amended herein. This listing of the claims replaces all previously submitted claims listings.

1. (Currently Amended) A method for supporting wafers for singulation and pick-and-place, comprising:

providing a semiconductor wafer;

mounting an adhesive-coated tape to a surface of the semiconductor wafer;

gripping the semiconductor wafer along at least a portion of a continuous ~~periphery~~peripheral ring of material comprising at least in part semiconductor material ~~thereof~~;

singulating individual components from the semiconductor wafer, leaving ~~a ring of material comprising at least in part a material of the semiconductor wafer~~at least the at least the portion of the continuous peripheral ring of material along ~~the~~ a periphery thereof; and

removing at least some individual components from the adhesive-coated tape.

2. (Currently Amended) The method of claim 1, wherein gripping the semiconductor wafer along at least a portion of the continuous peripheral ring of material ~~periphery thereof~~ further includes gripping the semiconductor wafer by the ring of material during the removing of the at least some individual components.

3. (Previously Presented) The method of claim 1, further including forming the ring of material only from the material of the semiconductor wafer.

4. (Previously Presented) The method of claim 1, further including forming at least a portion of the ring of material from a polymer material disposed about and contiguous with a periphery of the semiconductor wafer and of thickness at least as great as a thickness of the semiconductor wafer.

5. (Previously Presented) The method of claim 1, further including forming the ring of material in part from the material of the semiconductor wafer and in part from a polymer disposed about and contiguous with a periphery of the semiconductor wafer and of thickness at least as great as a thickness of the semiconductor wafer.

6. (Original) The method of claim 5, further comprising forming the ring of material from the polymer material by one of spin-coating, stereolithography or molding.

7. (Original) The method of claim 1, further comprising backgrinding the semiconductor wafer prior to singulation.

8. (Original) The method of claim 7, further comprising mounting the adhesive-coated tape to an active surface of the semiconductor wafer and singulating the semiconductor wafer from a backside thereof after backgrinding.

9. (Original) The method of claim 7, further comprising mounting the adhesive-coated tape to a backside of the semiconductor wafer and singulating the semiconductor wafer from an active surface thereof.

10. (Original) The method of claim 1, further comprising mounting the adhesive-coated tape to a backside of the semiconductor wafer and singulating the semiconductor wafer from an active surface thereof.

11. (Original) The method of claim 1, wherein mounting the adhesive-coated tape comprises mounting a tape bearing a UV-sensitive adhesive thereon.

12. (Previously Presented) The method of claim 11, further comprising exposing the UV-sensitive adhesive prior to removing the at least some individual components while leaving a portion on the adhesive-coated tape extending over the ring of material unexposed.

13. (Original) The method of claim 1, wherein the semiconductor wafer is singulated using one of laser cutting, water cutting and sawing.

14. (Original) The method of claim 1, further comprising discarding the ring of material, any remaining individual components and the adhesive-coated tape after removing the at least some individual components.

15 – 24. (Canceled)

25. (Currently Amended) A method for processing a semiconductor wafer, comprising:

mounting an adhesive-coated tape to a surface of a semiconductor wafer; and

singulating individual components from the semiconductor wafer, leaving an uncut ring of material comprising at least in part semiconductor material along a periphery of the semiconductor wafer and removing at least some singulated individual components without using a film frame while the adhesive-coated tape is mounted to the surface thereof.

26. (Currently Amended) The method of claim 25, ~~wherein the semiconductor wafer is~~ further comprising selecting the semiconductor wafer to be a 300 mm semiconductor wafer and ~~further including~~ handling the 300 mm semiconductor wafer using equipment sized to handle 200 mm semiconductor wafers.

27. (Original) The method of claim 26, further including singulating the 300 mm semiconductor wafer using a 200 mm semiconductor wafer saw chuck.

28. (Original) The method of claim 26, further including holding the 300 mm semiconductor wafer in a 200 mm semiconductor wafer pick-and-place machine chuck while removing the at least some singulated individual components therefrom.

29. (Currently Amended) A method of processing a semiconductor wafer, comprising:

gripping a semiconductor wafer along at least a portion of a ~~periphery thereof~~continuous peripheral ring of material comprising at least in part semiconductor material; and

singulating individual components from the semiconductor wafer while leaving ~~an uncut~~ at least the at least the portion of the continuous peripheral ring of material uncut ~~comprising at least in part a material of the semiconductor wafer thereabout~~.

30. (Original) The method of claim 29, further including removing at least some singulated individual components therefrom.

31. (Currently Amended) The method of claim 30, wherein gripping a semiconductor wafer along at least a portion of a ~~periphery thereof~~continuous peripheral ring of material further includes gripping the uncut peripheral ring of material while removing the at least some singulated individual components therefrom.

32. (Original) The method of claim 29, further comprising defining the uncut peripheral ring of material from semiconductor material.

33. (Previously Presented) The method of claim 29, further comprising defining the uncut peripheral ring of material at least in part from a polymer disposed about and contiguous with the semiconductor wafer.

34. (Previously Presented) The method of claim 29, further comprising defining the uncut peripheral ring of material in part from semiconductor material and in part from a polymer disposed about and contiguous with a periphery of the semiconductor wafer.

35. (Currently Amended) The method of claim 30, ~~wherein the semiconductor wafer is~~ further comprising selecting a 300 mm semiconductor wafer and ~~further including~~ handling the 300 mm semiconductor wafer using equipment sized to handle 200 mm semiconductor wafers.

36. (Original) The method of claim 35, further including singulating the 300 mm semiconductor wafer using a 200 mm semiconductor wafer saw chuck.

37. (Original) The method of claim 35, further including holding the 300 mm semiconductor wafer in a 200 mm semiconductor wafer pick-and-place machine chuck while removing the at least some singulated individual components therefrom.

38. (Previously Presented) A method of using a 300 mm semiconductor wafer, including handling the 300 mm semiconductor wafer with equipment sized to handle 200 mm semiconductor wafers.

39. (Original) The method of claim 38, further including processing the 300 mm semiconductor wafer with equipment sized to handle 200 mm semiconductor wafers.

40 - 41. (Canceled)